










APPLICABLE STANDARD					
RATING	OPERATING TEMPERATURE RANGE	-55 °C TO 85 °C ⁽¹⁾	STORAGE TEMPERATURE RANGE	-10 °C TO 60 °C ⁽²⁾	
	VOLTAGE	100 V AC	STORAGE HUMIDITY RANGE	40 % TO 70 % ⁽²⁾	
	CURRENT	0.5 A (SIGNAL CONTACT) ⁽³⁾  3 A (MF CONTACT) 	OPERATING HUMIDITY RANGE	RELATIVE HUMIDITY 85% max (NOT DEWED)	
SPECIFICATIONS					
ITEM	TEST METHOD	REQUIREMENTS	QT	AT	
CONSTRUCTION					
GENERAL EXAMINATION	VISUALLY AND BY MEASURING INSTRUMENT.	ACCORDING TO DRAWING.	x	x	
MARKING	CONFIRMED VISUALLY.		x	x	
ELECTRIC CHARACTERISTICS					
CONTACT RESISTANCE	100 mA(DC OR 1000Hz)	SIGNAL CONTACT : 90 mΩ MAX. MF CONTACT : 30 mΩ MAX. 	x	-	
INSULATION RESISTANCE	250 V DC.	1000 MΩ MIN.	x	-	
VOLTAGE PROOF	300 V AC FOR 1 min.	NO FLASHOVER OR BREAKDOWN.	x	-	
MECHANICAL CHARACTERISTICS					
INSERTION AND WITHDRAWAL FORCES	MEASURED BY APPLICABLE CONNECTOR.	INSERTION FORCE: 40 N MAX. WITHDRAWAL FORCE: 4 N MIN.	x	-	
MECHANICAL OPERATION	500 TIMES INSERTIONS AND EXTRACTIONS.	① CONTACT RESISTANCE: SIGNAL CONTACT : 100 mΩ MAX. MF CONTACT : 40 mΩ MAX.  ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x	-	
VIBRATION	FREQUENCY 10 TO 55 TO 10Hz, APPROX 5min SINGLE AMPLITUDE : 0.75 mm, 10 CYCLES FOR 3 DIRECTIONS.	① NO ELECTRICAL DISCONTINUITY OF 1 μs. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x	-	
SHOCK	490 m/s ² , DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.	① NO ELECTRICAL DISCONTINUITY OF 1 μs. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x	-	
ENVIRONMENTAL CHARACTERISTICS					
DAMP HEAT (STEADY STATE)	EXPOSED AT 40±2 °C, 90 ~ 95 %, 96 h.	① CONTACT RESISTANCE: SIGNAL CONTACT : 100 mΩ MAX. MF CONTACT : 40 mΩ MAX. 	x	-	
RAPID CHANGE OF TEMPERATURE	TEMPERATURE -55 → +85 °C TIME 30 → 30 min. UNDER 5 CYCLES. (RELOCATION TIME TO CHAMBER: WITHIN 2~3 MIN)	② INSULATION RESISTANCE :1000 MΩ MIN. ③ NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x	-	
SULFUR DIOXIDE	EXPOSED AT 25±2°C, 75±5%RH, 25 PPM FOR 96 h. (TEST STANDARD: JIS C 60068)	NO HEAVY CORROSION.	x	-	
RESISTANCE TO SOLDERING HEAT	1)REFLOW SOLDERING : PEAK TMP : 260°C MAX REFLOW TMP: 220°C MIN FOR 60sec 2) SOLDERING IRONS : 360°C MAX. FOR 5 sec.	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINAL.	x	-	
SOLDERABILITY	SOLDERED AT SOLDER TEMPERATURE 240±3°C FOR IMMERSION DURATION, 3 sec.	A NEW UNIFORM COATING OF SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMersed.	x	-	
COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE	
 6	DIS-F-004173	TH. SANO	KI. HIROKAWA	09. 09. 15	
REMARKS ⁽¹⁾ INCLUDE TEMPERATURE RISE CAUSED BY CURRENT-CARRYING. ⁽²⁾ "STORAGE" MEANS A LONG-TERM STORAGE STATE FOR THE UNUSED PRODUCT BEFORE ASSEMBLY TO PCB. ⁽³⁾ THE RATED CURRENT APPLIES TO PER CONTACT.  Unless otherwise specified, refer to JIS-C-5402.		APPROVED	HS. OKAWA	09. 04. 28	
		CHECKED	HS. OZAWA	09. 04. 28	
		DESIGNED	KI. HIROKAWA	09. 04. 28	
		DRAWN	KI. HIROKAWA	09. 04. 28	
Note	QT:Qualification Test AT:Assurance Test X:Applicable Test	DRAWING NO.	ELC4-159561-00		
	SPECIFICATION SHEET	PART NO.	FX18-60P-0. 8SV		
	HIROSE ELECTRIC CO., LTD.	CODE NO.	CL579-0017-2-00		1/1